

Dual P-Channel 2.5-V (G-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	r _{DS(on)} (Ω)	I _D (A)			
-20	$0.995 @ V_{GS} = -4.5 V$	±0.44			
	1.190 @ V _{GS} = -3.6 V	±0.40			
	1.80 @ V _{GS} = -2.5 V	±0.32			

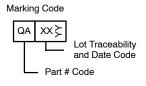
FEATURES

- TrenchFET[®] Power MOSFET
- 2.5-V Rated
- Lead (Pb)-Free Version is RoHS Compliant



SC-70 (6-LEADS) S_1 1 6 D_1 G_1 2 5 G_2 D_2 3 4 S_2 Top View

SOT-363



Ordering Information: Si1903DL-T1

Si1903DL-T1—E3 (Lead (Pb)-Free)

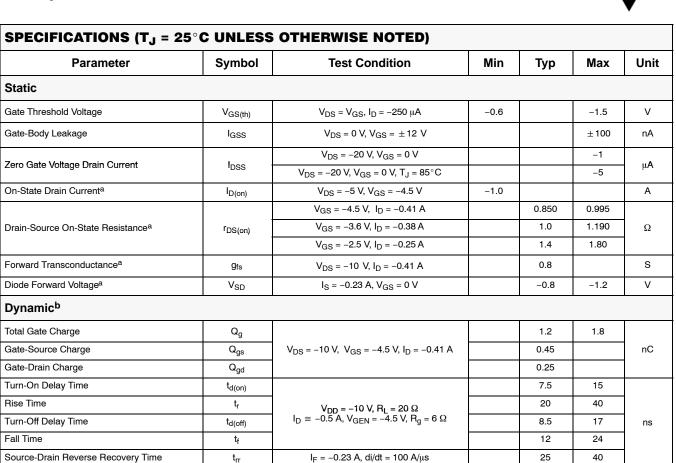
ABSOLUTE MAXIMUM RATINGS (T _A = 25°C UNLESS OTHERWISE NOTED)									
Parameter		Symbol	5 secs	Steady State	Unit				
Drain-Source Voltage		V _{DS}	-20		v				
Gate-Source Voltage		V _{GS}	±12						
Continuous Drain Current (T, J = 150°C) ^a	$T_A = 25^{\circ}C$	Ι _D	±0.44	±0.41	А				
	T _A = 85°C		±0.31	±0.30					
Pulsed Drain Current		I _{DM}	±1.0		<i>N</i>				
Continuous Diode Current (Diode Conduction) ^a		۱ _S	-0.25	-0.23					
Mariana Davia Diasia Aliang	$T_A = 25^{\circ}C$	– P _D	0.30	0.27	w				
Maximum Power Dissipation ^a	$T_A = 85^{\circ}C$		0.16	0.14					
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55	to 150	°C				

THERMAL RESISTANCE RATINGS								
Parameter		Symbol	Typical	Maximum	Unit			
	$t \le 5 \text{ sec}$	R _{thJA}	360	415	°C/W			
Maximum Junction-to-Ambient ^a	Steady State		400	460				
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	300	350				

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

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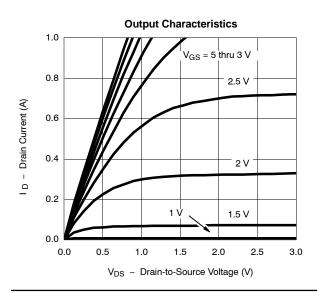
Notes

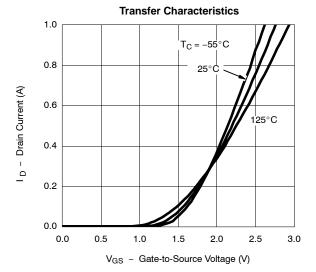
a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2%.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

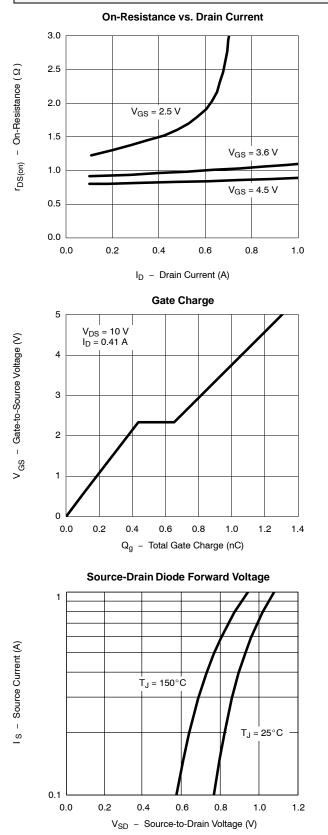


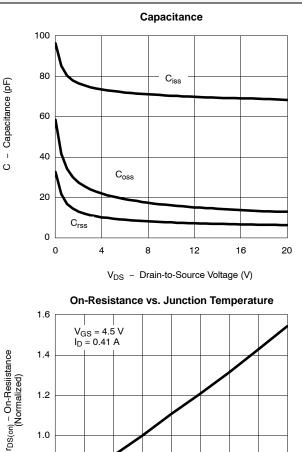




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TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)







50

T_J – Junction Temperature (°C)

75

100

125 150

1.0

0.8

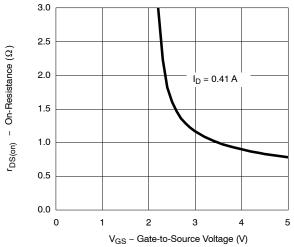
0.6

-50

-25

0

25

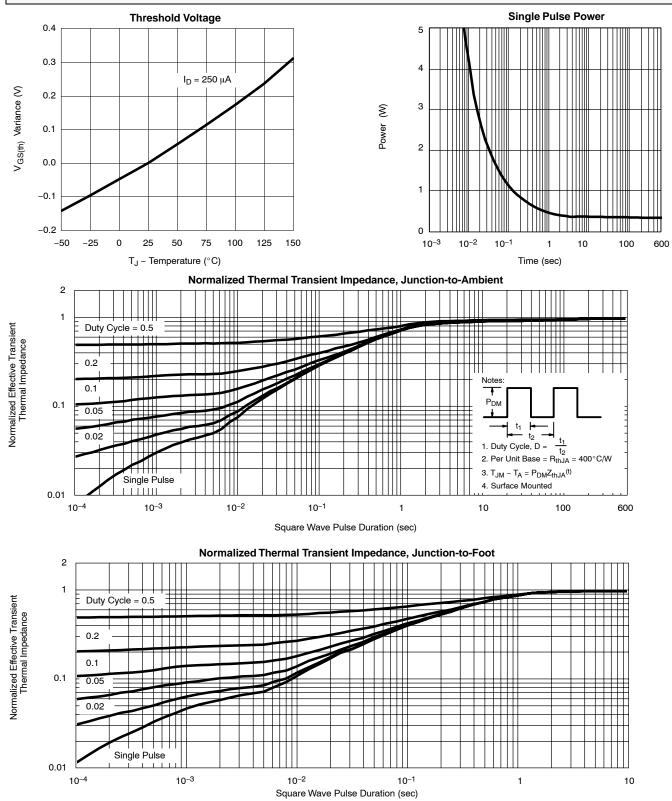


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TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)



Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?71081.



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